



## Material Content Data Sheet



<b>Sales Product Name</b>				BTN8982TA		<b>Issued</b>		24. January 2018	
<b>MA#</b>				MA001936852					
<b>Package</b>				PG-TO263-7-1		<b>Weight*</b>		1532.41 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	7.214	0.47	0.47	4708	4708	
leadframe	inorganic material	phosphorus	7723-14-0	0.243	0.02		159		
	non noble metal	iron	7439-89-6	0.810	0.05		528		
wire	non noble metal	copper	7440-50-8	808.613	52.78	52.85	527673	528360	
	non noble metal	aluminium	7429-90-5	6.176	0.40	0.40	4030	4030	
encapsulation	organic material	carbon black	1333-86-4	8.791	0.57		5737		
	plastics	epoxy resin	-	96.702	6.31		63104		
	inorganic material	silicondioxide	60676-86-0	480.578	31.36	38.24	313609	382450	
leadfinish	non noble metal	tin	7440-31-5	13.037	0.85	0.85	8507	8507	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
	non noble metal	nickel	7440-02-0	0.212	0.01	0.01	139	140	
glue	plastics	Polyimide	26023-21-2	0.396	0.03	0.03	259	259	
solder	non noble metal	tin	7440-31-5	0.066	0.00		43		
	noble metal	silver	7440-22-4	0.082	0.01		54		
	non noble metal	lead	7439-92-1	3.141	0.20	0.21	2050	2147	
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		21		
	non noble metal	iron	7439-89-6	0.106	0.01		69		
	non noble metal	copper	7440-50-8	106.210	6.93	6.94	69309	69399	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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